

## Description

The XXW1N60G uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



SOT-223

## General Features

$V_{DS} = 600V$   $I_D = 1A$

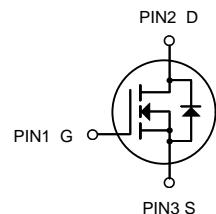
$R_{DS(ON)} < 12\Omega$  @  $V_{GS}=10V$

## Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

## Absolute Maximum Ratings ( $T_C=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	600	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	1	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	4.8	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	1	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	62.5	°C/W

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	600	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.057	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=0.6\text{A}$	---	9.5	12	$\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	2	---	4	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-5.68	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=650\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=650\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 30\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=0.5\text{A}$	---	35	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.7	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{\text{DS}}=520\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=1\text{A}$	---	4	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	0.9	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	2.5	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=325\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=50\Omega$ , $I_D=1\text{A}$	---	4	---	ns
$T_r$	Rise Time		---	24	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	6	---	
$T_f$	Fall Time		---	24	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	119	---	pF
$C_{\text{oss}}$	Output Capacitance		---	19	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	2	---	
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	1	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	4.8	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.4	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=15\text{A}$ , $dl/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	160	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	0.3	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=0.1\text{mH}$ , $I_{\text{AS}}=28\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature 5.The data is theoretically the same as  $I_D$  and  $l_{\text{DM}}$  , in real applications , should be limited by total power dissipation

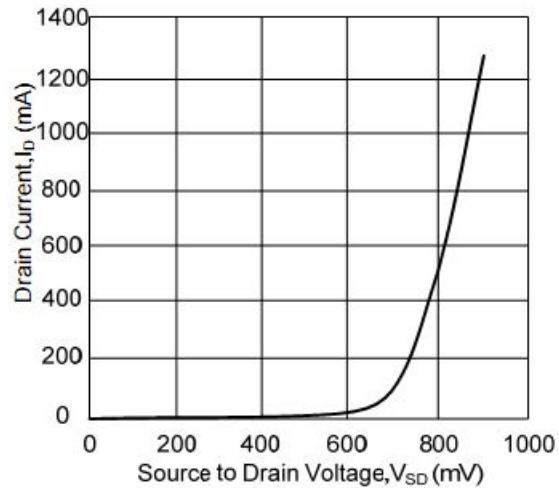
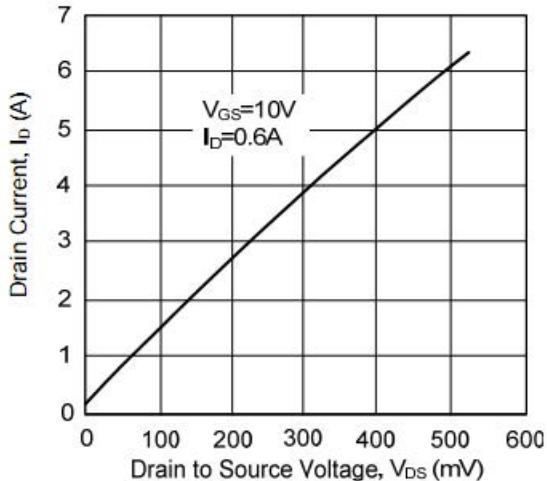
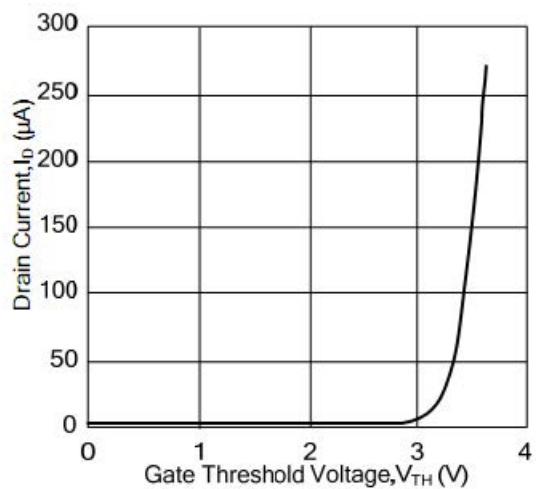
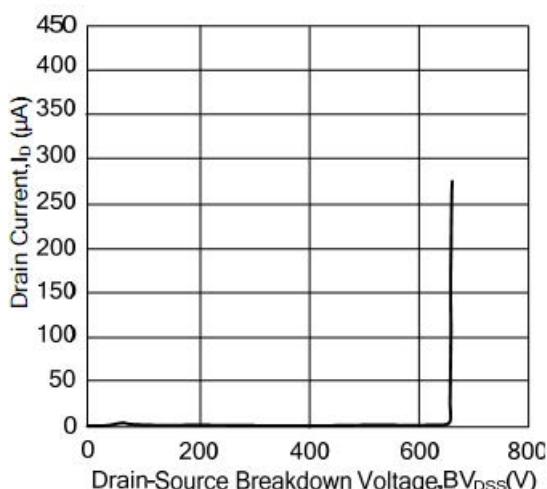
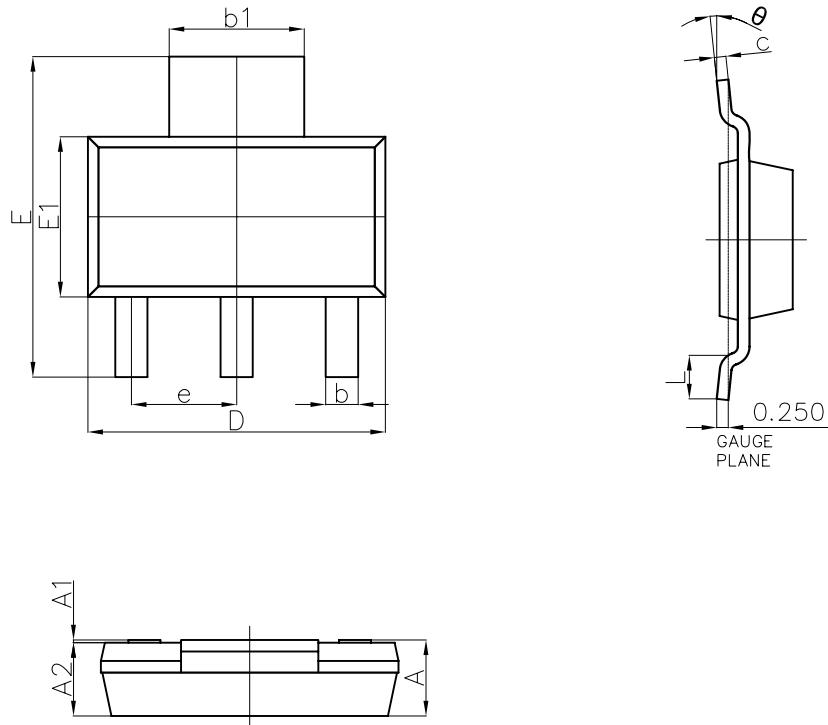
**Typical Characteristics**


Fig1.Drain Current vs. Source to Drain Voltage


 Fig2. Resistance Characteristics  
 Drain-Source On-State

 Fig3.Gate Threshold Voltage  
 Drain Current vs.

 Fig4.Drain-Source Breakdown Voltage  
 Drain Current vs.

**SOT-223 Package Outline Dimensions**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	—	1.800	—	0.071
A1	0.020	0.100	0.001	0.004
A2	1.500	1.700	0.059	0.067
b	0.660	0.840	0.026	0.033
b1	2.900	3.100	0.114	0.122
c	0.230	0.350	0.009	0.014
D	6.300	6.700	0.248	0.264
E	6.700	7.300	0.264	0.287
E1	3.300	3.700	0.130	0.146
e	2.300(BSC)		0.091(BSC)	
L	0.750	—	0.030	—
θ	0°	10°	0°	10°